

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A manufacturing method for a liquid crystal display panel panels having a high aperture ratio, comprising ~~the steps of~~:

providing a transparent substrate with thin film transistors formed forming therein, and ~~the~~ a periphery of the transparent substrate having an outer lead bonding area formed by covering an insulation layer over metal wires;

forming a protection layer over the thin film transistors of the transparent substrate and the outer lead bonding area;

applying a photo-etching process [[by]] using a half-tone mask to the protection layer so as to form openings respectively above the thin film transistors and at the outer lead bonding area, wherein remove a part of the protection layer at the outer lead bonding area for exposing the insulation layer on which at the outer lead bonding pads are predefinedly located area is exposed through the openings; and

expanding the openings by further etching the remaining protection layer and the exposed insulation layer for exposing upper portions of the insulation layer and generating so as to form via holes through the insulation layer so as to expose exposing

portions of the thin film transistors and the metal wires.

Claim 2 (Canceled)

Claim 3 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture ratio of Claim 1 [[2]], further comprising ~~the step of~~ forming a transparent conductive layer on the protection layer and inside the via holes so as to electrically contact the thin film transistors.

Claim 4 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture of Claim 1, wherein the thin film transistors are transistors transistor is a transistor having an etching stop structure.

Claim 5 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture ratio of Claim 1, wherein the thin film transistors are transistors transistor is a transistor having a back-channel etching structure.

Claim 6 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture of Claim 1, wherein the exposed portions of the metal wires are [[the]] outer lead bonding pads.

Claim 7 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture of Claim 1, wherein the protection layer is made from a transparent organic material.

Claim 8 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture of Claim 7, wherein the transparent organic material is acrylate.

Claim 9 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture ratio of Claim 1, further comprising ~~the step of[[:]]~~ sealing the liquid crystal display panel by pasting a sealant on the ~~exposed portions of~~ the insulation layer at the outer lead bonding area.

Claim 10 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture ratio of Claim 1, further comprising ~~the step of[[:]]~~ interposing a silicon nitride layer between the insulation layer and the protection layer.

Claim 11 (Currently Amended): The manufacturing method for a liquid crystal display panel panels having a high aperture ratio of Claim 1, wherein the protection layer is a photoresist layer.